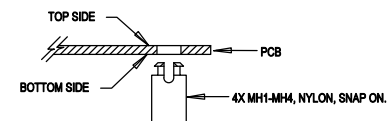


EVAL-LTC7891-AZ
HIGH FREQUENCY, STEP-DOWN
SUPPLY WITH GaN FET

TOP SILKSCREEN
ANALOG DEVICES
EVAL-LTC7891-AZ REV 1
DATE: 8-25-2023

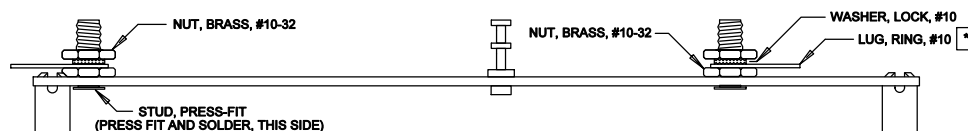
NOTES: UNLESS OTHERWISE SPECIFIED


1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AS SHOWN BELOW:



8. INSTALL STUD HARDWARE SET AS SHOWN BELOW:

- * FACE RING LUG AT EDGE OF THE BOARD.



 ANALOG DEVICES			
TITLE: TOP ASSEMBLY DRAWING HIGH FREQUENCY, STEP DOWN SUPPLY WITH GaN FET			
SIZE	IC NO.	LTC7891	REV.
N/A	EVAL-LTC7891-AZ		1
FILENAME:			SHT 1 OF 2